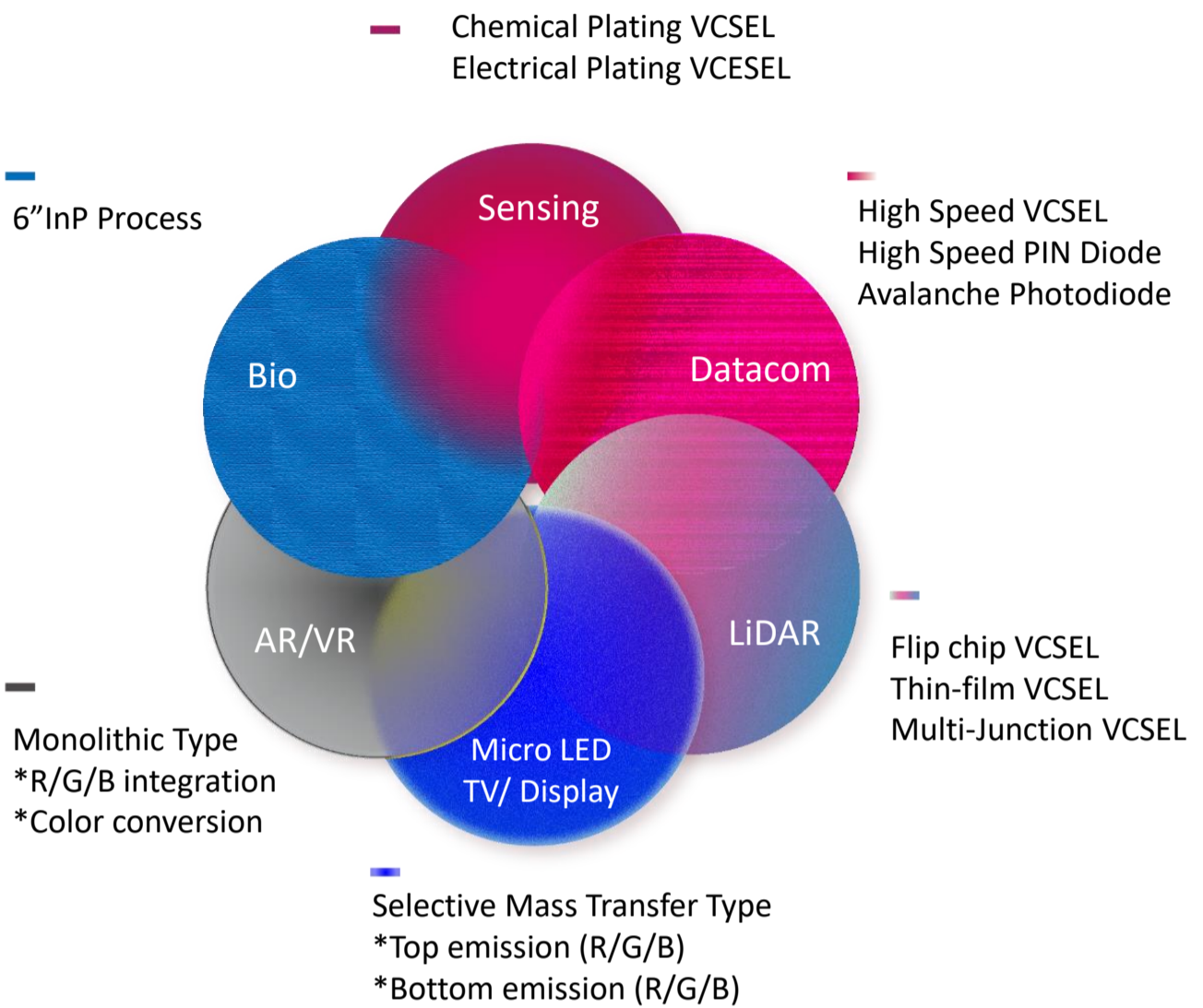


Foundry Solutions

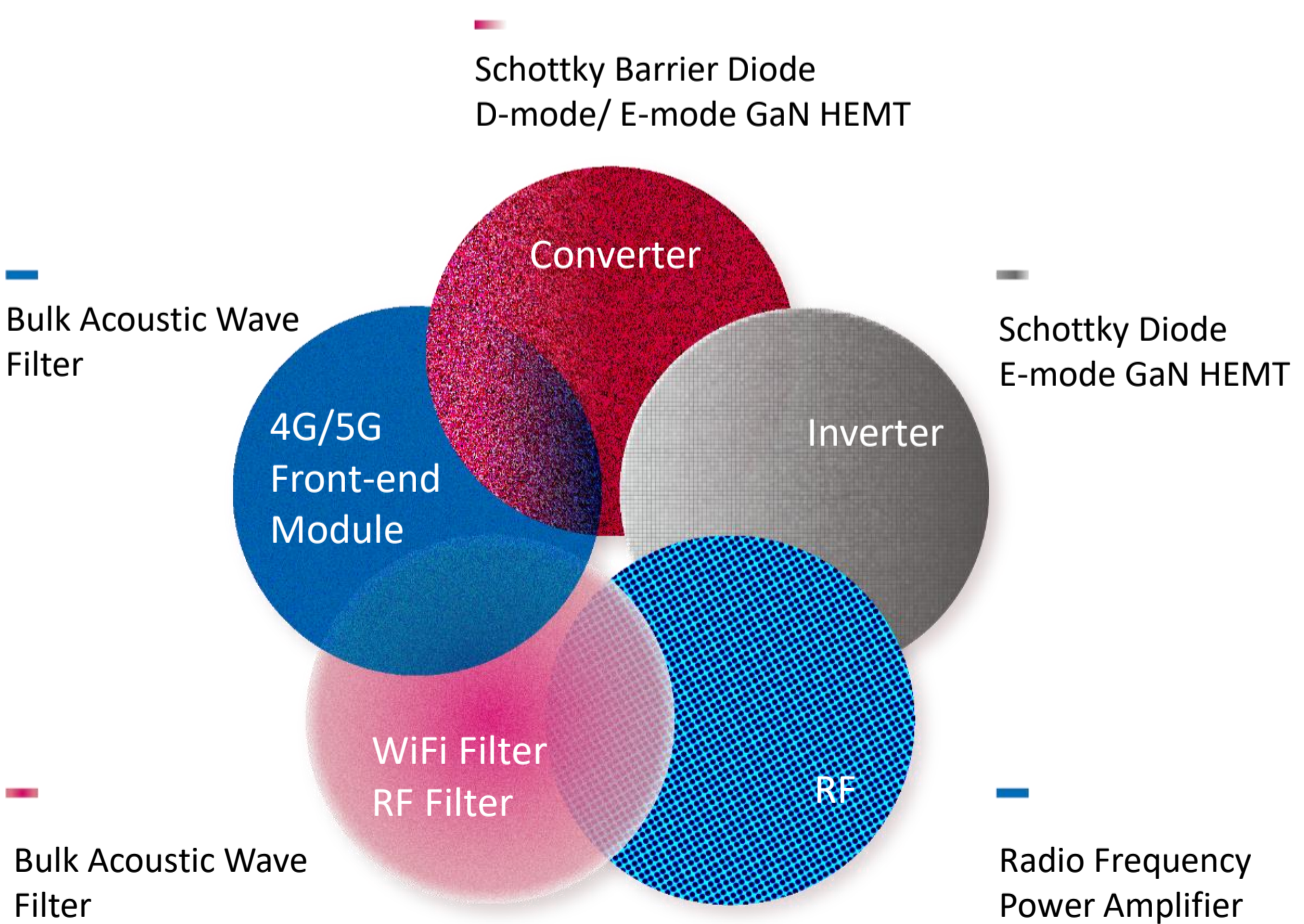
Optoelectronic Device



Special Process:

- Wafer Bonding
- Lithography Depth of Focus
- Thick Photoresist
- Metal Interconnection
- Current Spreading Design
- Submicron Capability

Microelectronic Device



Special Process:

- GaN on Si, Al₂O₃, SiC, AlN
- Shallow Etch Precise Controllability
- MEMS Structure
- Trimming
- Through Silicon Via
- Wafer Level Package
- Process Design Kit Ready (BAW)